



SOD-123FL

Plastic, surface-mounted package; 2 terminals;
3 mm x 1.9 mm x 1 mm body

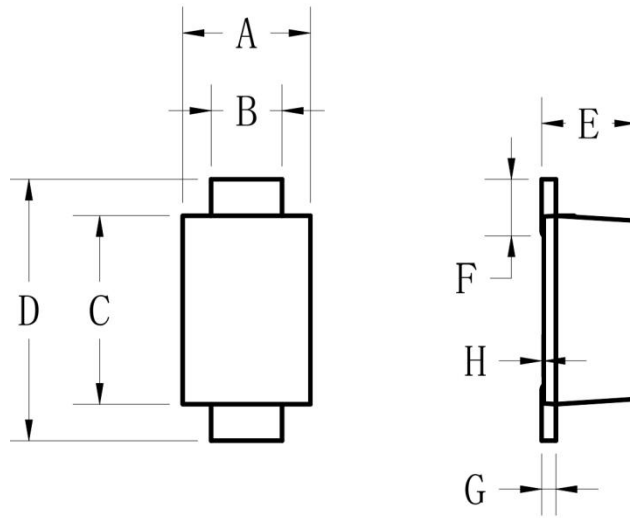
塑料表面贴装封装；2 引脚；
封装本体尺寸 3 mm x 1.9 mm x 1 mm

1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	SOD-123FL
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	3mm × 1.9mm × 1mm body 封装本体（不含引脚）尺寸为 3mm × 1.9mm × 1mm
Terminals Compliance 引脚合规	2 terminals, Tin Plated Leads, Solderable per MILSTD-202, Method 208 ^③ 2 个镀锡引脚，可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.0169 grams (Approximate) 约 0.0169 克

2. Package Outline Dimensions 封装外形尺寸

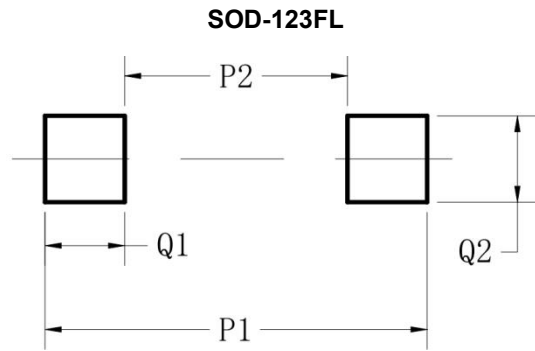
SOD-123FL



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	1.75	1.95
B	0.80	1.10
C	2.60	2.90
D	3.55	3.75
E	0.95	1.15
F	0.55	0.85
G	0.12	0.20
H	0.02	0.05



3. Suggested Pad Layout 推荐焊盘布局



Dimensions 尺寸	Millimeters 毫米
P1	3.90
P2	1.90
Q1	1.00
Q2	1.50

Fig. Soldering footprint for SOD-123FL

图 SOD-123FL 的引脚焊接

4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
7	8	3000

Note:

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

说明: 上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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